

Harvatek Surface Mount LEDs Data Sheet HT-F104TW

Official Product	HT-F104TW	Your Part No.		Data Sheet No.
		*****		HT-F104TW
Specifications are subjective without advance notice. company confidential all responses to the second sec	June 25, 2013	Version 1.0	Page 1/18	

harvatek technologies

DISCLAIMER	3
PRODUCT SPECIFICATION	4
ATTENTION: ELECTRICSTATIC DISCHARGE (ESD) PROTECTION	4
LABEL SPEC	5
PRODUCT CHARACTERISTICS	9
ELECTRO-OPTICAL CHARACTERISTICS Package Outline Dimension Absolute Maximum Ratings	9
CHARACTERISTICS CURVES1	0
PACKAGING TAPE, REEL, AND PACKING MODEL1	2
TAPE DIMENSION 1 REEL DIMENSION 1 TAPE LEADER AND TRAILER DIMENSION 1	2
PACKING MODEL 1	.3
Dry Pack	4
CAUTIONS OF PICK AND PLACE1	.5
PRECAUTIONS1	.5
Soldering Pattern	6 6 6
CLEANING	7
REVISION HISTORY1	8

Official Product	HT-F104TW	Your Part No.		Data Sheet No.
		*****	HT-F104TW	
Specifications are subj without advance notice. company confidential all i	June 25, 2013	Version 1.0	Page 2/18	

HARVATEK TECHNOLOGIES

DISCLAIMER

HARVATEK reserves the right to make changes without further notice to any products herein to improve reliability, function or design. HARVATEK does not assume any liability arising out of the application or use of any product or circuit described herein; neither does it convey any license under its patent rights, nor the rights of others.

LIFE SUPPORT POLICY

HARVATEK's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President of HARVATEK or HARVATEK INTERNATIONAL. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.

2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

Official Product	HT-F104TW	Your Part No.		Data Sheet No.
		*****		HT-F104TW
Specifications are subjection without advance notice. company confidential all r	June 25, 2013	Version 1.0	Page 3/18	



Product Specification

	Specification	Material	Quantity
lv	2000mcd typ.		
	@20mA/ Ta= 25 ⁰ C		
	Tolerance: <u>+</u> 10%		
Chromaticity	Refer to page 8		
Coordinates	@20mA/ Ta= 25 ⁰ C		
	Tolerance: <u>+</u> 0.01		
Vf	3.4V max		
	@20mA/ Ta= 25 ⁰ C		
	Tolerance: <u>+</u> 0.05V		
Resin	Yellow	Silicone resin	
ESD	500V (HBM)		
Carrier tape	According to EIA 481-1A specs	Conductive black tape	1000pcs per reel
Reel	According to EIA 481-1A specs	Conductive black	
Label	HT standard	Paper	
Packing bag	220x240mm	Aluminum laminated bag/ no-zipper	One reel one bag
Carton	HT standard	Paper	Non-specified
	Specification	Material	Quantity

Others:

Every mid-box will be loaded 5 reels. These 5 reels can be different in lot, lv, lambda, or Vf. Every reel will have an independent label to identify its specification and the mid-box there will have a corresponding label post on it.

ATTENTION: Electricstatic Discharge (ESD) protection



The symbol shown on the page herein to introduce 'Electro-Optical Characteristics'. ESD protection for GaP and AlGaAs based chips is still necessary even though they are safe in low static-electric discharge. Parts built

with AllnGaP, GaN, or/and InGaN based chips are **STATIC SENSITIVE devices**. ESD protection has to considered and taken in the initial design stage.

If manual work/process is needed, please ensure the device is well protected from ESD during all the process.

Official Product	HT-F104TW	Your Part No.		Data Sheet No.	
		******		HT-F104TW	
	ect to changes for improvement Proprietary data, drawings, and ights reserved.	June 25, 2013	Version 1.0	Page 4/18	



Label Spec.

HARVATEK TECHNOLOGIES	A	Date: yyyy/mm/dd
CUSTOMER P/N:		
HARVATEK P/N:		QTY: PCS
LOT NO:		
		QC
IV BIN: COLOR BIN:		

 \checkmark

Harvatek P/N

H T - F 1 0 4 TW - XXXX

Series Name	Emitting Color	Custom code
HT-F104:	TW:	XXXX
3.8x1.0x0.4mm	White@20mA	Customer product code

√

Official Product	HT-F104TW	Your Part No.		Data Sheet No.
		****		HT-F104TW
Specifications are subjection without advance notice. company confidential all r	June 25, 2013	Version 1.0	Page 5/18	

Lot No.

1	2	3	4	5	6	7	8	9	10
Ε	1	Α	1	Α	2	2	L	1	2
Code 1	12	Code 3	Code 4	Code 5	Code 6	Code 7	Code 8	Code 9	Code 10
		Mfg. Year	Mfg. Month	Mfg. Date	Consecuti	ve number		Special code	
Internal Trac	ing Code	2010-A 2011-B 2012-C 2013-D	1:Jan. 2:Feb. A:Oct. B:Nov. C:Dec.	1:A 2:B 3:C 26:Z 27:7 28:8 29:9 30:3 31:4	01-	-72		000~ZZZ	

Official Product	HT-F104TW	Your Part No.		Data Sheet No.
		*****		HT-F104TW
Specifications are subjourned without advance notice. company confidential all responses to the second sec	June 25, 2013	Version 1.0	Page 6/18	

Luminous Intensity (Iv) Bin:

Bin	Luminous Inten	sity Range (mcd)
ып	Minimum	Maximum
Z42	1700	1800
Z51	1800	1900
Z52	1900	2010
Z61	2010	2125
Z62	2125	2250

@20mA / Ta=25[°] C, Tolerance: <u>+</u> 10%

Forward Voltage (V_F) Bin:

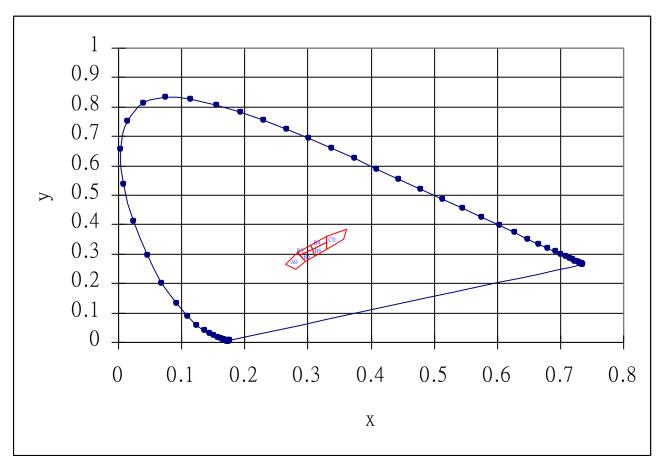
Bin	Range
H2	2.9 – 3.0V
Н3	3.0 – 3.1V
H4	3.1 – 3.2V
J1	3.2 – 3.3V
J2	3.3 – 3.4V

@20mA / Ta=25[°] C, Tolerance: <u>+</u> 0.05 V

Official Product	HT-F104TW	Your Part No.		Data Sheet No.
		*****		HT-F104TW
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, and company confidential all rights reserved.		June 25, 2013	Version 1.0	Page 7/18

XY Chromaticity Bin:

	Bin Code	Spec. Range					
	Bin Code	(x ₁ ,y ₁)	(x ₂ ,y ₂)	(x ₃ ,y ₃)	(x₄,y₄)		
	В3	0.307,0.315	0.287,0.295	0.304,0.330	0.283,0.305		
Color	B4	0.307,0.315	0.330,0.339	0.330,0.360	0.304,0.330		
	B5	0.296,0.276	0.287,0.295	0.307,0.315	0.311,0.294		
	В6	0.311,0.294	0.307,0.315	0.330-0.339	0.330,0.318		
	C0	0.330,0.318	0.330,0.360	0.361,0.385	0.356,0.351		
@20mA / Ta=25 [°] C, + 0.01							



@20mA / Ta=25⁰ C, Tolerance: <u>+</u> 0.01

Official Product	HT-F104TW	Your Part No.		Data Sheet No.
		*****		HT-F104TW
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, and company confidential all rights reserved.		June 25, 2013	Version 1.0	Page 8/18

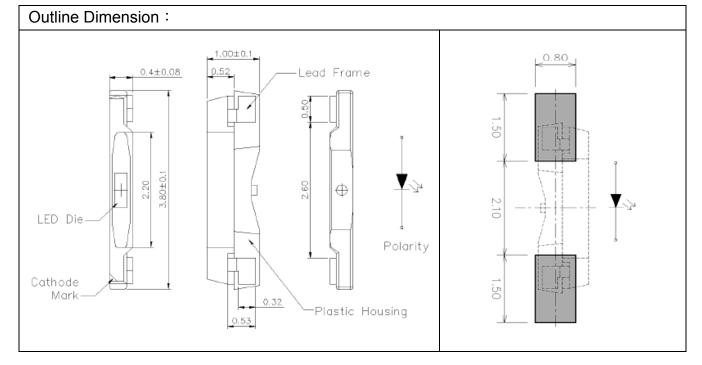
Product Characteristics

Electro-Optical Characteristics								
(I _F @ 20mA, T _a 25 °C)								
Product No.			λ (nm)		l [*] _v (mcd)			
	Color	wateria	Тур.	max	λD	λp	$ riangle \lambda$	Тур.
HT-F104TW	White	InGaN	3.2	3.4	X=0.31 Y=0.33			2000

* Per NIST standards

Package Outline Dimension

Unit: mm Tolerance: +/-0.01



Absolute Maximum Ratings							
						(T _a 25 ^o C)	
Series	P _d (mW)	I _F (mA)	I _{FP} (mA)	Ir (μA) @ V _R = 5 V	T _{OP} (°C)	T _{ST} (°C)	
HT-F104TW	117	25	100	<1µA	-30~+85	-40~+100	

* Condition for $I_{\mbox{\scriptsize FP}}$ is pulse of 1/10 duty and 0.1msec width

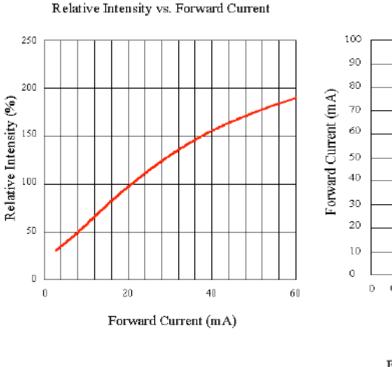
**Remarks: This product should be operated in forward bias. If a reverse voltage is continuously applied to the product,

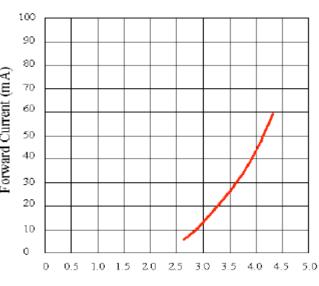
such operation can cause migration resulting in LED damage.

Official Product	HT-F104TW	Your Part No.		Data Sheet No.
		*****		HT-F104TW
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, and company confidential all rights reserved.		June 25, 2013	Version 1.0	Page 9/18

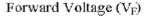


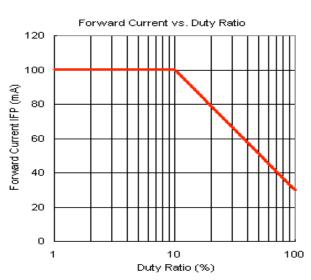
Characteristics Curves

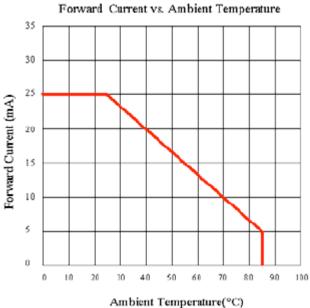




Forward Voltage vs. Forward Current

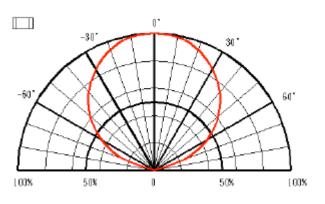


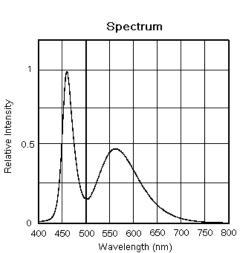




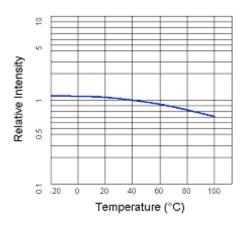
Official Product	HT-F104TW	Your Part No.		Data Sheet No.
		****		HT-F104TW
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, and company confidential all rights reserved.		June 25, 2013	Version 1.0	Page 10/18



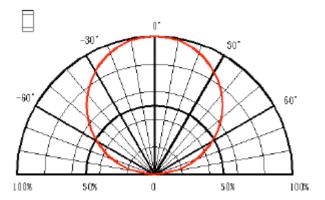




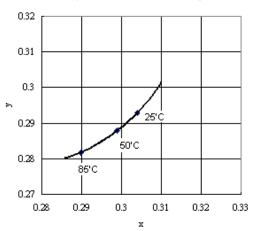
Relative Intensity vs. Ambient Temperature



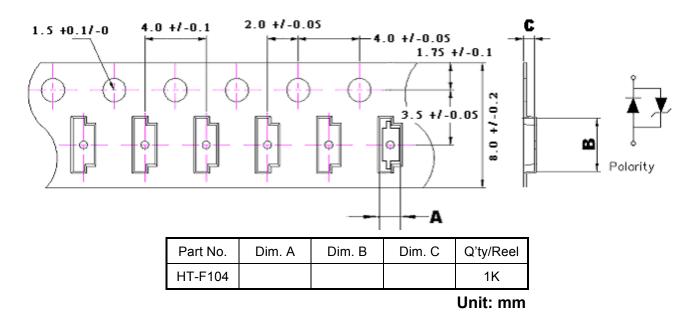
Official Product	HT-F104TW	Your Part No.		Data Sheet No.
		*****		HT-F104TW
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, and company confidential all rights reserved.		June 25, 2013	Version 1.0	Page 11/18



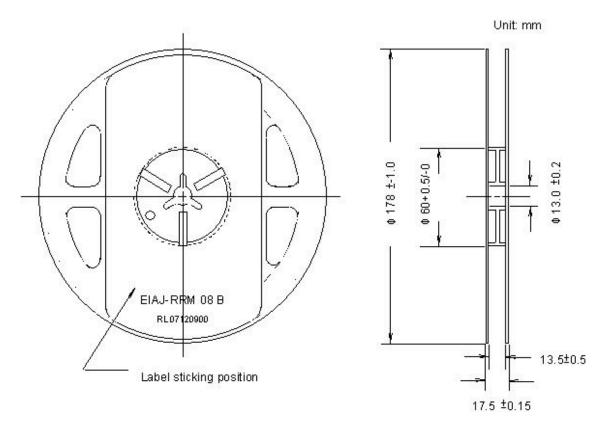
Ambient Temperature vs. Chromaticity Coordinate



Packaging Tape, Reel, and Packing Model Tape Dimension



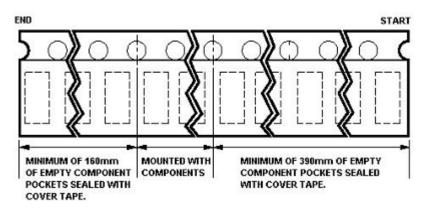
Reel Dimension



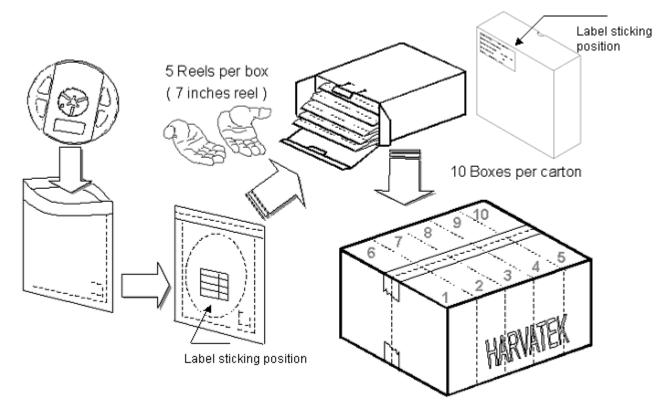
Official Product	HT-F104TW	Your Part No.		Data Sheet No.
		*****		HT-F104TW
without advance notice.	Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, and company confidential all rights reserved.		Version 1.0	Page 12/18



Tape Leader and Trailer Dimension



Packing Model



5 boxes per carton is available according to shipping quantity.

Cardboard Box	Dimensions(cm)	Reel/box	Quantity/box
Size			(pcs)
Small	45 x 26 x 30	25 reels Max.	50, 000 Max
Large	50 x 46 x 30	50 reels Max.	100, 000 Max

Official Product	HT-F104TW	Your Part No.		Data Sheet No.
		*****		HT-F104TW
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, and company confidential all rights reserved.		June 25, 2013	Version 1.0	Page 13/18

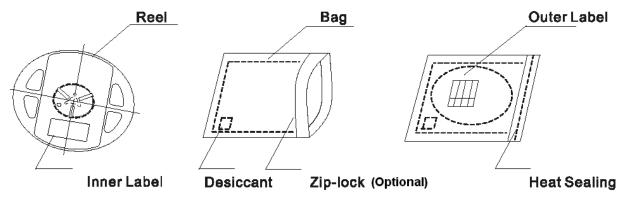


Dry Pack

Any SMD optical device, like this chip LED, is **MOISTURE SENSITIVE device**. Avoid absorbing moisture at any time during transportation or storage. Every reel will be packaged in the moisture barrier anti-static bag (Specific bag material will depend upon customers' requirement or option). And the bag is well sealed before shipment.

By customer's requirement, we will put a humidity indicator in each moisture barrier anti-static bag before shipment.

The package is the following:



Storage

It's recommended to store the products in the following conditions:

Humidity: 60 %RH Max.

Temperature: $5^{\circ}C \sim 30^{\circ}C (41^{\circ}F \sim 86^{\circ}F)$

- 1 Shelf life in sealed bag: 12 month at<40 ^oC and <90%RH. (Base on aluminum laminated moisture barrier bag.)
- 2 After the bag is opened, devices that will be subjected to infrared reflow, vapor-phase reflow, or equivalent processing must be:
 - 2.1 Mounted within 72 hours at factory conditions of $\leq~$ 30 ^{O}C /60% RH, or
 - 2.2 Stored at \leq 20% RH with zip-lock sealed.

Official Product	HT-F104TW	Your Part No.		Data Sheet No.
		*****		HT-F104TW
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, and company confidential all rights reserved.		June 25, 2013	Version 1.0	Page 14/18



Baking

It's recommended to bake before soldering when the pack is unsealed after 15 days. The conditions are as followings:

- a) 60 $\pm 3^{\circ}$ Cx(12~24hrs) and < 5% RH, taped reel type
- b) 100±3°C×(45min~1hr), bulk type
- c) 130±3^oC×(15~30min), bulk type

Cautions of Pick and Place

It should be avoided to load stress on the resin during high temperature.

Avoid rubbing or scraping the resin by any object.

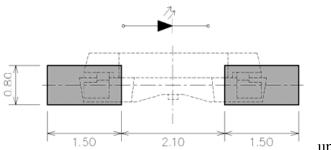
Electric-static may cause damage to the component. Please confirm that the equipment grounding well. Using an ionizer fan is recommended.

PRECAUTIONS

- 1. Avoid absorbing moisture at any time during transportation or storage.
- 2. Anti-Static process is needed especially when handling GaN, InGaN, and AlInGaP products.
- 3. It is suggested to connect the unit with a proper series current limit resistor. Avoid driving reverse voltage over the specification of LEDs when turning the unit ON/OFF.
- 4. Any application should refer to the specifications of absolute maximum ratings.
- 5. Avoid any direct contact with the viewing area.
- 6. If possible, assemble the unit in a clean room or dust-free environment.

Soldering pattern

The dimensions of the recommended soldering pattern may not meet every user. Please confirm and study first before designing the soldering pattern in order to obtain the best performance of soldering. Recommended soldering pattern is listed below.



unit: mm

Soldering terminal may shift in x, y direction.

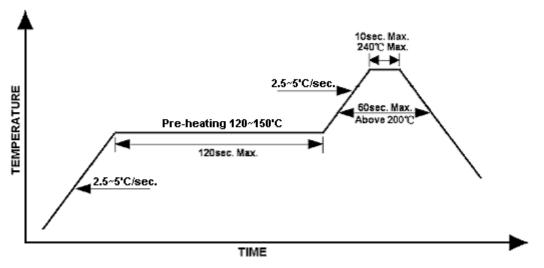
Official Product	HT-F104TW	Your Part No.		Data Sheet No.
		*****		HT-F104TW
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, and company confidential all rights reserved.		June 25, 2013	Version 1.0	Page 15/18



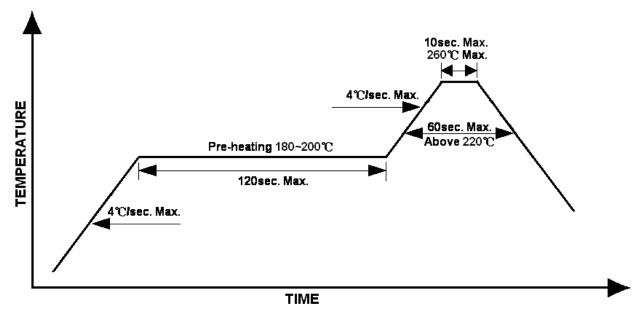
Re-flow Soldering

- Recommend tin glue specifications: Melting temperature: 178~192 ^oC
- Never take next process until the component is cooled down to room temperature after re-flow.
- The recommended re-flow soldering profile (measuring on the surface of the LED resin) is following:

Lead Solder







Official Product	HT-F104TW	Your Part No.		Data Sheet No.
		*****		HT-F104TW
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, and company confidential all rights reserved.		June 25, 2013	Version 1.0	Page 16/18



Rework

- Customer must finish rework within 5 sec. under 260 °C.
- The head of iron cannot touch copper foil.
- Twin-head type is preferred.

Cleaning

The conditions of cleaning after soldering:

An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.

TemperaturexTime: <50 ^oCx30sec, or <30 ^oCx3min

Ultra sonic cleaning: < 15W/ bath; Bath volume: 1liter max.

Curing: 100 °C max, <3min

Do not contact with component on the assembly board.

Official Product	HT-F104TW	Your Part No.		Data Sheet No.
		*****		HT-F104TW
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, and company confidential all rights reserved.		June 25, 2013	Version 1.0	Page 17/18



Revision History

Changes since last revision	Pa	ge	Version No.	Revision Date
Initial Release			V1.0	06-25-2013

Official Product	HT-F104TW	Your Part No.		Data Sheet No.
		*****		HT-F104TW
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, and company confidential all rights reserved.		June 25, 2013	Version 1.0	Page 18/18